

Title (en)

Wafer spacing mask for a substrate support chuck and method of fabricating same

Title (de)

Distanzstück-Maske für Plättchen auf einer Substratträger-Spannvorrichtung und Herstellungsverfahren dafür

Title (fr)

Masque de séparation de plaquette pour un mandrin support de substrat et procédé de fabrication

Publication

**EP 0794566 B1 20021106 (EN)**

Application

**EP 97301502 A 19970306**

Priority

US 61265296 A 19960308

Abstract (en)

[origin: US5656093A] A wafer spacing mask for supporting a workpiece in a spaced apart relation to a workpiece support chuck. More specifically, the wafer spacing mask contains a plurality of metallic support members deposited upon the support surface of the chuck. The support members maintain a wafer, or other workpiece, in a spaced apart relation to the support surface of the chuck. The distance between the underside surface of the wafer and the chuck is defined by the thickness of the support members. This distance should be larger than the expected diameter of contaminant particles that may lie on the surface of the chuck. In this manner, the contaminant particles do not adhere to the underside of the wafer during processing.

IPC 1-7

**H01L 21/68**; **H01L 21/00**

IPC 8 full level

**H02N 13/00** (2006.01); **B23Q 3/15** (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP KR US)

**H01L 21/027** (2013.01 - KR); **H01L 21/6831** (2013.01 - EP US); **Y10S 269/903** (2013.01 - EP US); **Y10T 279/23** (2015.01 - EP US)

Cited by

EP0806798A3; EP0806797A3; EP0856882A3; US6217655B1; US9640514B1; WO02103761A1

Designated contracting state (EPC)

AT BE CH DE ES FR GB GR IE IT LI NL SE

DOCDB simple family (publication)

**EP 0794566 A1 19970910**; **EP 0794566 B1 20021106**; AT E227471 T1 20021115; DE 69716796 D1 20021212; DE 69716796 T2 20030731; JP 3266537 B2 20020318; JP H09327188 A 19971216; KR 100274768 B1 20010115; KR 970067579 A 19971013; US 5656093 A 19970812

DOCDB simple family (application)

**EP 97301502 A 19970306**; AT 97301502 T 19970306; DE 69716796 T 19970306; JP 5125597 A 19970306; KR 19970007603 A 19970307; US 61265296 A 19960308